



(1,00 mm) .0394"

CLM, MLE SERIES

MLE-150-01-G-DV

MLE-120-01-G-DV

CLM-111-02-L-D

CLM-126-02-F-D

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM

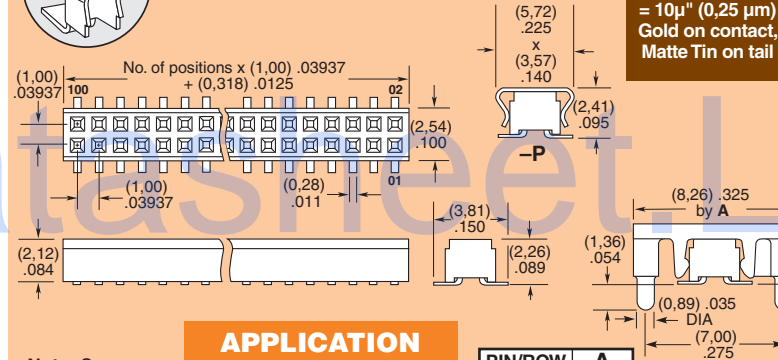
Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au, Sn or SnPb over 50µ" (1,27 µm) Ni
Current Rating: 3A per contact @ 80°C ambient
Operating Temp Range: -55°C to +125°C
Contact Resistance: 15 mΩ
Insertion Depth: Top Entry = (1,40 mm) .055" min., Bottom Entry = (2,41 mm) .095" min. (Add board thickness for correct post OAL)
Insertion Force: 1.5 oz (0,42 N) average
Normal Force: 40 grams (0,39 N) average
Withdrawal Force: .75 oz (0,21 N) average
Max Cycles: 100 with 10µ" (0,25 µm) Au
RoHS Compliant: Yes
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (02-25) (0,15 mm) .006" max (26-50)



Mates with: FTM, FTMH, MW

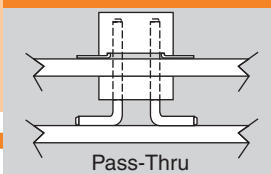


02 thru 50



Note: Some lengths, styles and options are non-standard, non-returnable.

APPLICATION



PIN/ROW	A
04-15	(3,56) .140
16-50	(7,11) .280

- F = Gold flash on contact, Matte Tin on tail
- L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail
- BE = Bottom Entry (Required for bottom entry)
- K = (3,50 mm) .138" DIA Polyimide film Pick & Place Pad (7 positions minimum)
- P = Pick & Place Pad (7 positions minimum)
- PA = Pick & Place Pad with integral Alignment Pin
- TR = Tape & Reel Packaging

APPLICATION SPECIFIC OPTION

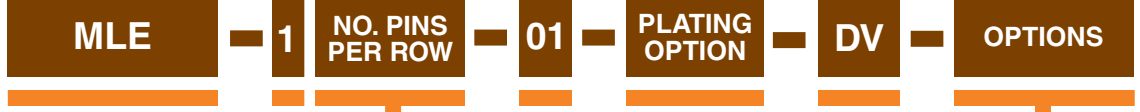
- Alignment Pin available.
- Other Gold plating options available.

Call Samtec.

SPECIFICATIONS

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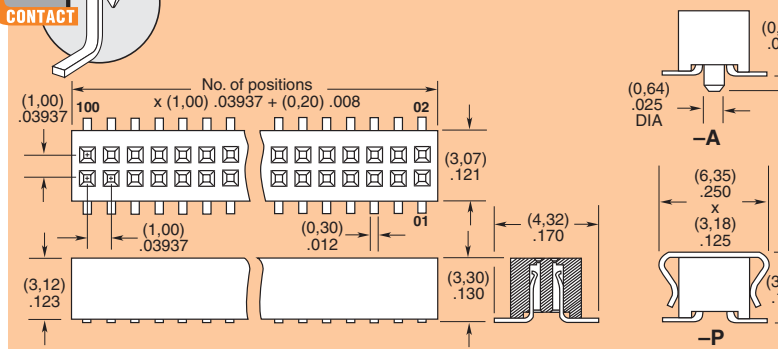
Insulator Material: Black LCP
Contact Material: BeCu
Operating Temp Range: -55°C to +125°C
Plating: Au over 10µ" (0,25 µm) Ni
Insertion Depth: (1,63 mm) .064" to (3,18 mm) .125" with (0,38 mm) .015" wipe, pass-through, or (2,44 mm) .096" minimum for bottom entry
Insertion Force: 2.70 oz (0,75 N) average
Withdrawal Force: 0.50 oz (0,14 N) average
RoHS Compliant: Yes
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (02-25) (0,15 mm) .006" max (26-50)



Mates with: FTM, FTMH, MW



02 thru 50



Note: Some lengths, styles and options are non-standard, non-returnable.

- G = 10µ" (0,25 µm) Gold
- A = Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion.
- K = (4,00 mm) .1575" DIA Polyimide film Pick & Place Pad (5 positions minimum)
- P = Metal Pick & Place Pad (5 positions minimum)
- TR = Tape & Reel Packaging

Due to technical progress, all designs, specifications and components are subject to change without notice.

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